



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP LD4210 42-inch LCD Digital Signage Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	3
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	20
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		8
External electrical cables and cords		4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
SCREW DRIVER	#2
Hexagonal inserted handle box wrench	
Pliers	
Description #4	
Description #5	

3.0 Product Disassembly Process

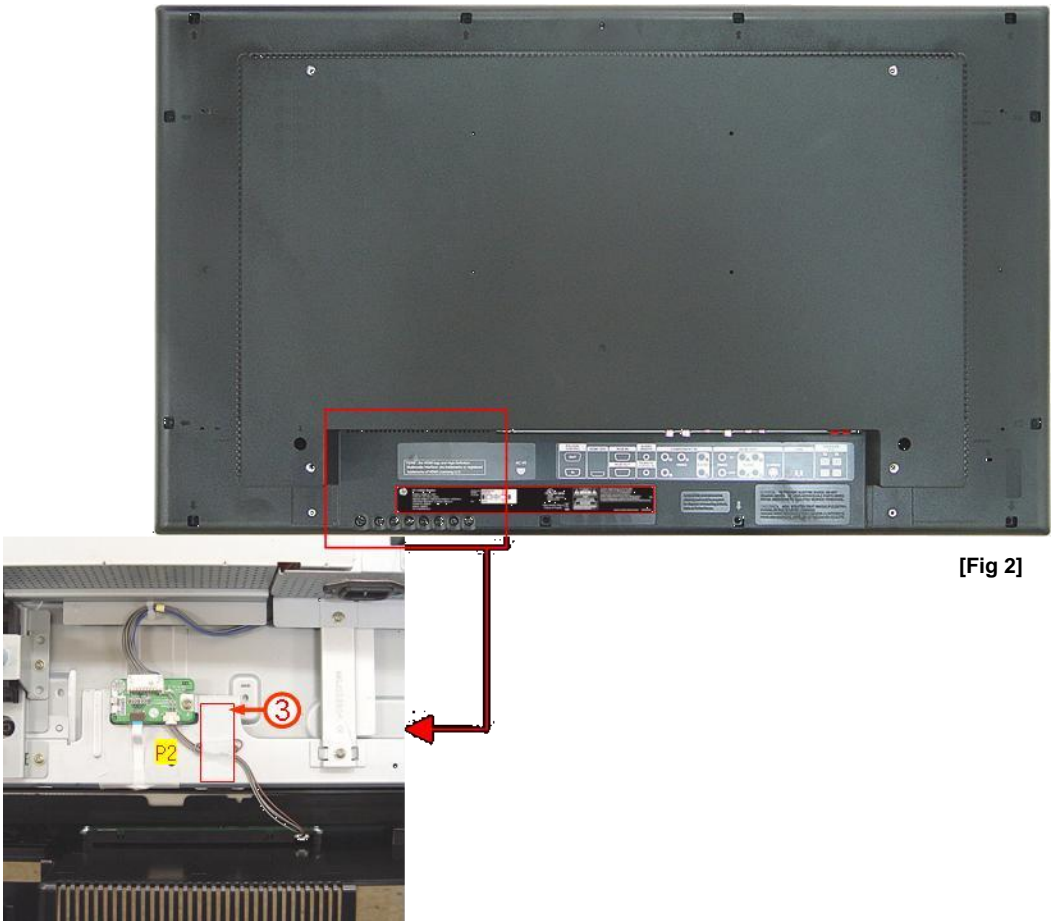
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unlock 12 screws to separate back cover assembly from cabinet assembly. [Fig.1]
2. Separate back cover control connector from speaker PCB P2. [Fig.2]
3. Detach tapes on harnesses and separate harnesses from module "A" [Fig.3]
4. Unlock 4 screws to separate chassis from LCD module. [Fig. 4]
5. Disassemble the LCD module to the cabinet assy. [Fig. 5]
6. Unlock 8 screws to separate plate from supporter. [Fig. 6]
7. Unlock 6 screws to separate fan assembly from plate and unlock 6 screws to disassemble FFC cable from main pcb. [Fig. 7]
8. 1) Unlock 4 screw to separate power pcb from Supporter . 2) Unlock 1 screw to separate sub pcb from supporter. 3) Separate 2 holder from power PCB [Fig. 8]
9. 1) Unlock 10 screws to separate vesa bracket and stand supporter from Supporter . 2) Separate 1EA rubber from supporter . [Fig. 9]
10. 1) Unlock 16 screw from supporter. [Fig. 10]

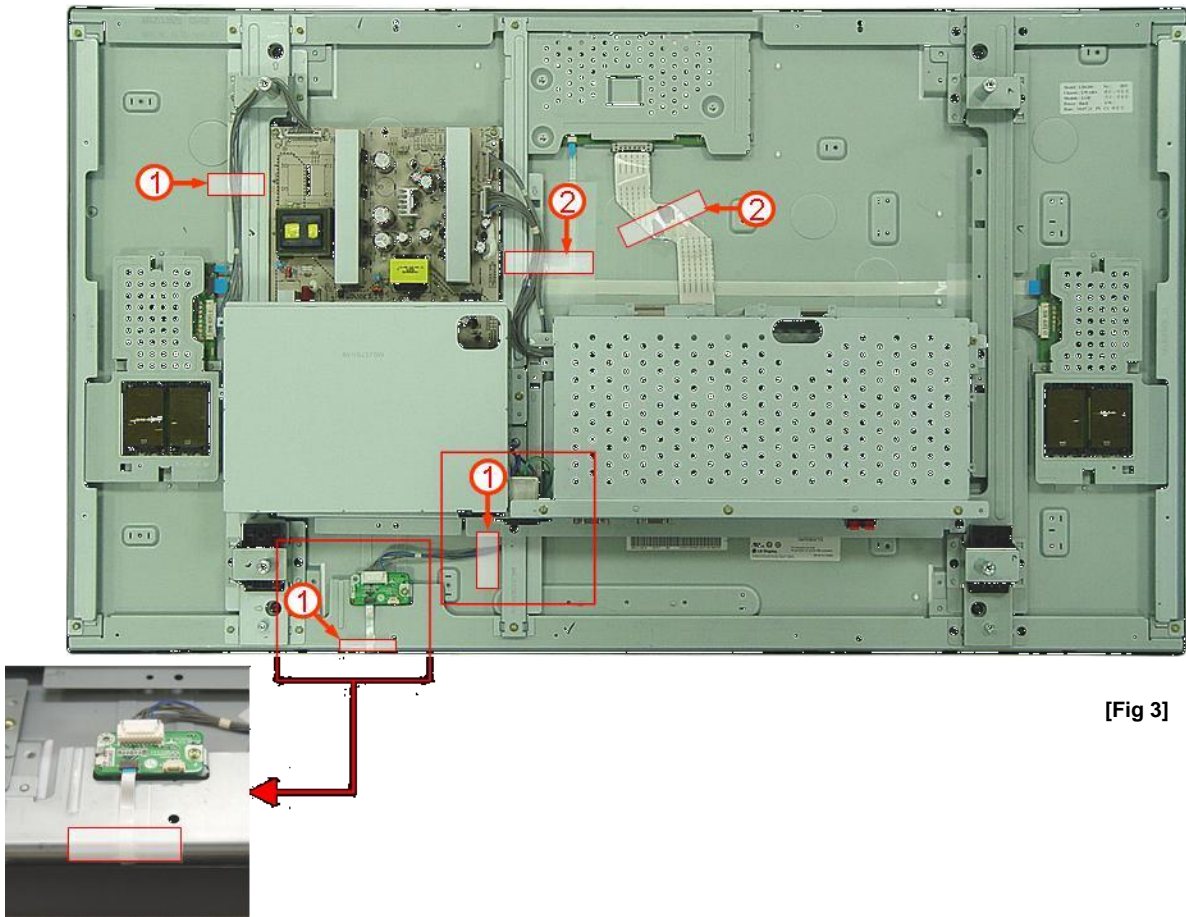
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



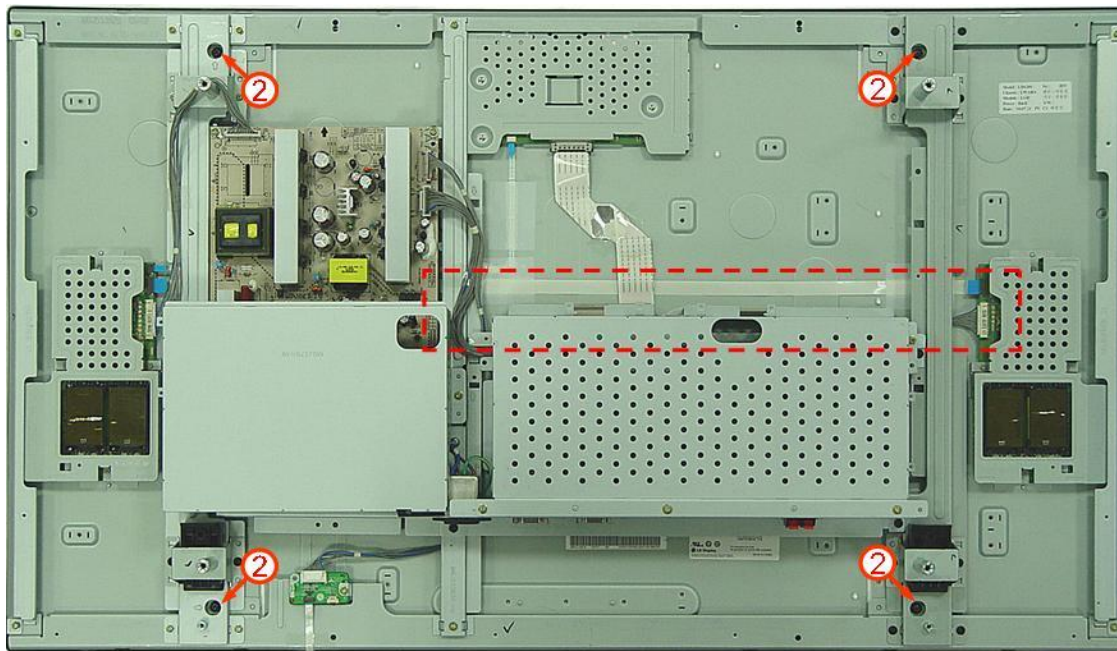
[Fig 1]



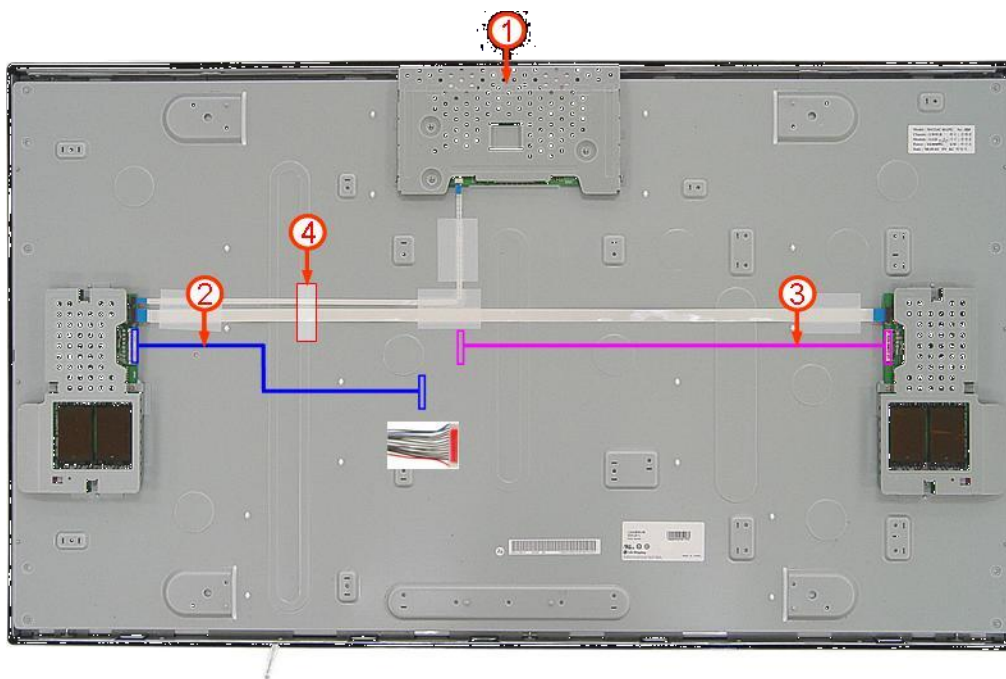
[Fig 2]



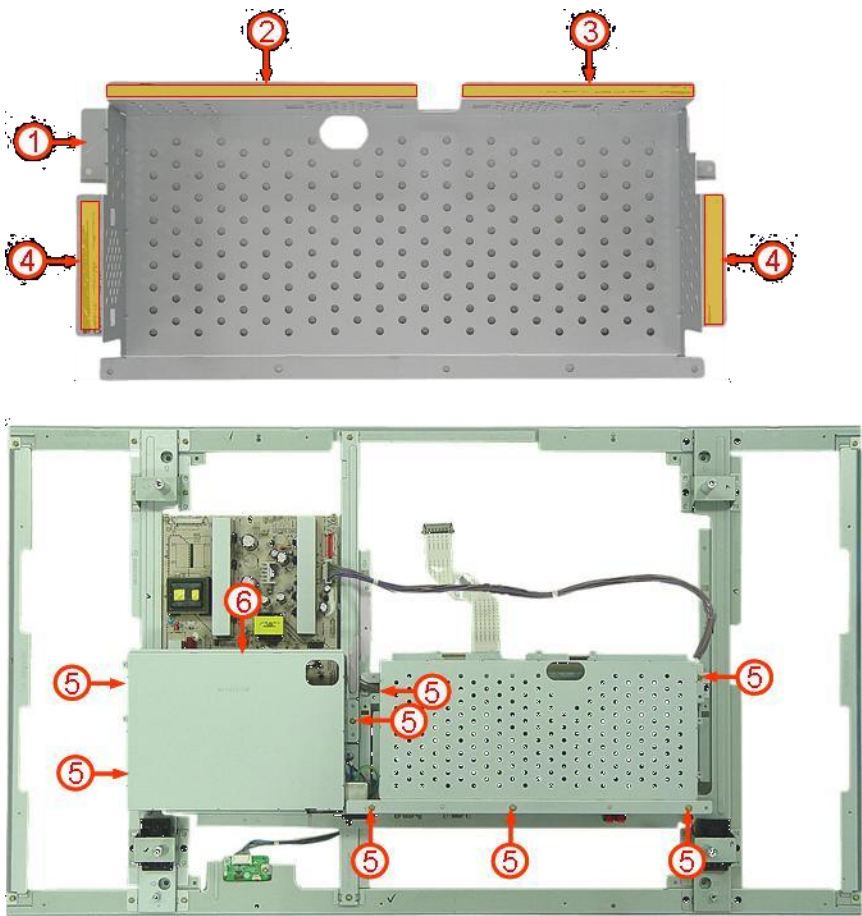
[Fig 3]



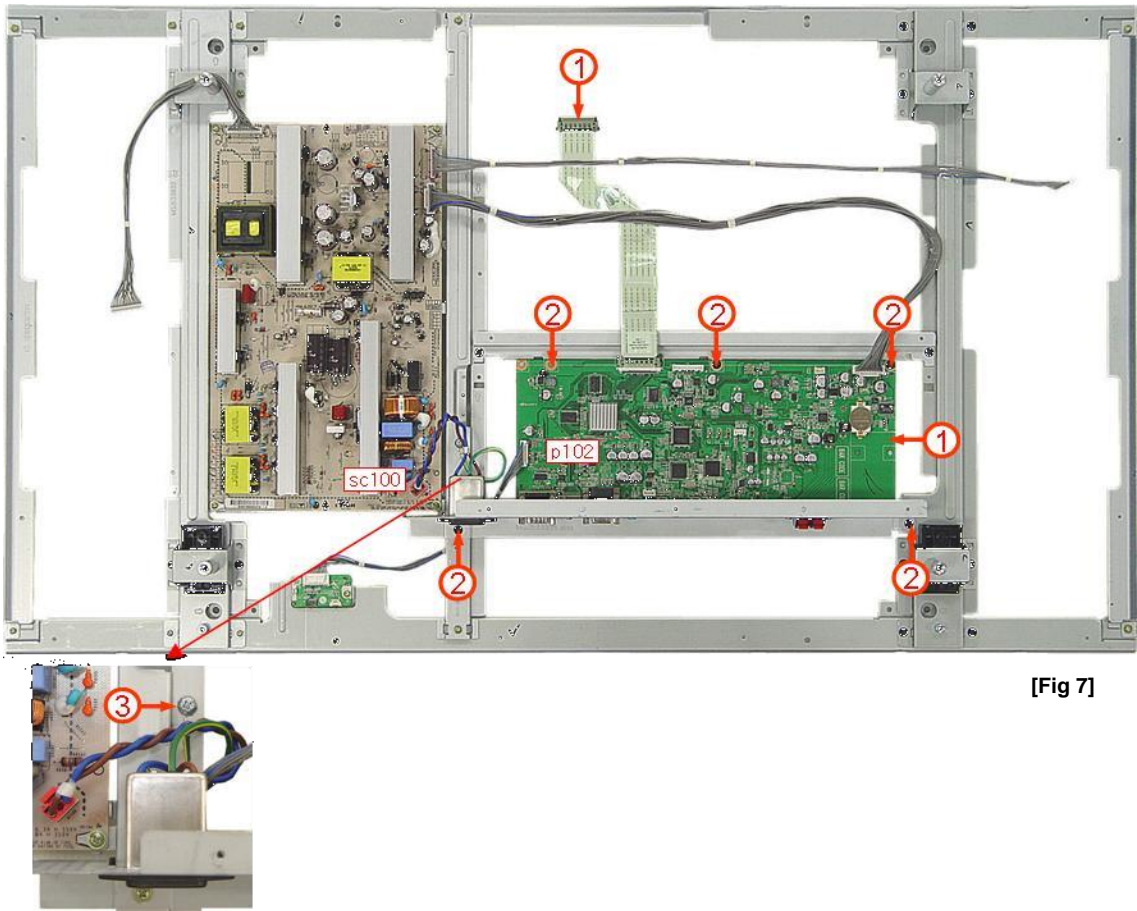
[Fig 4]



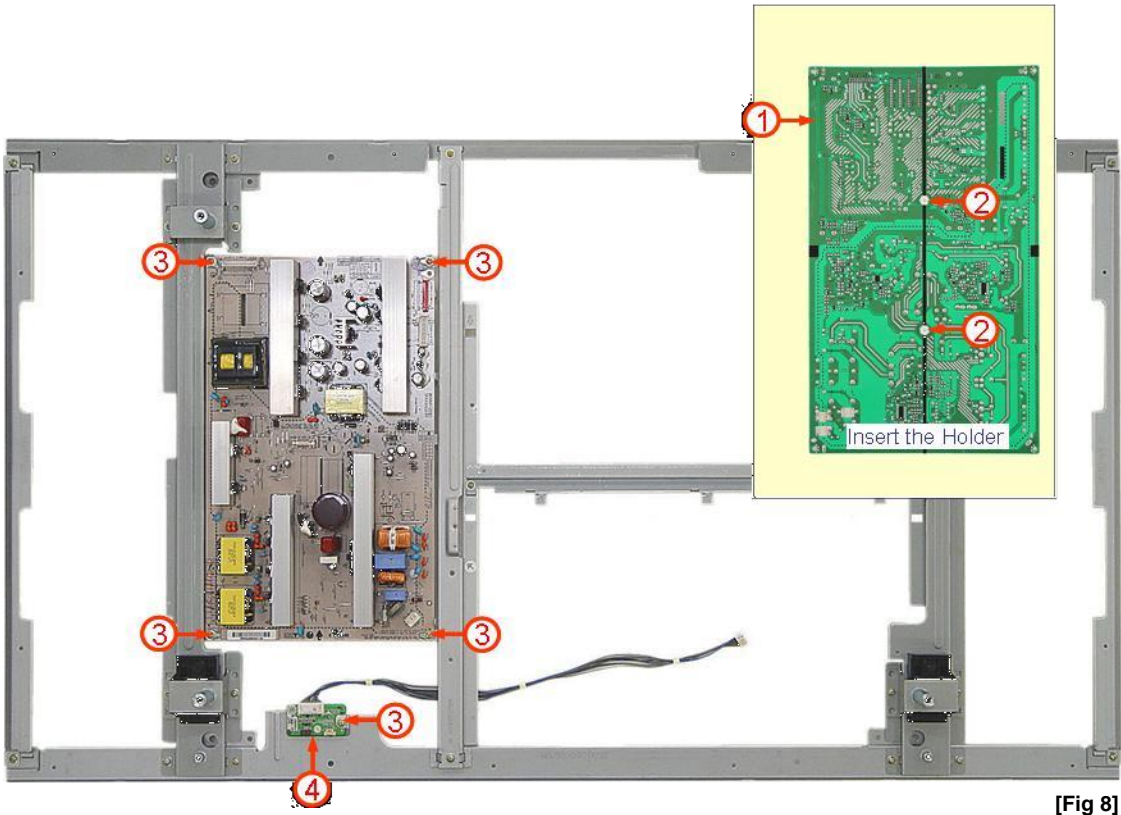
[Fig 5]



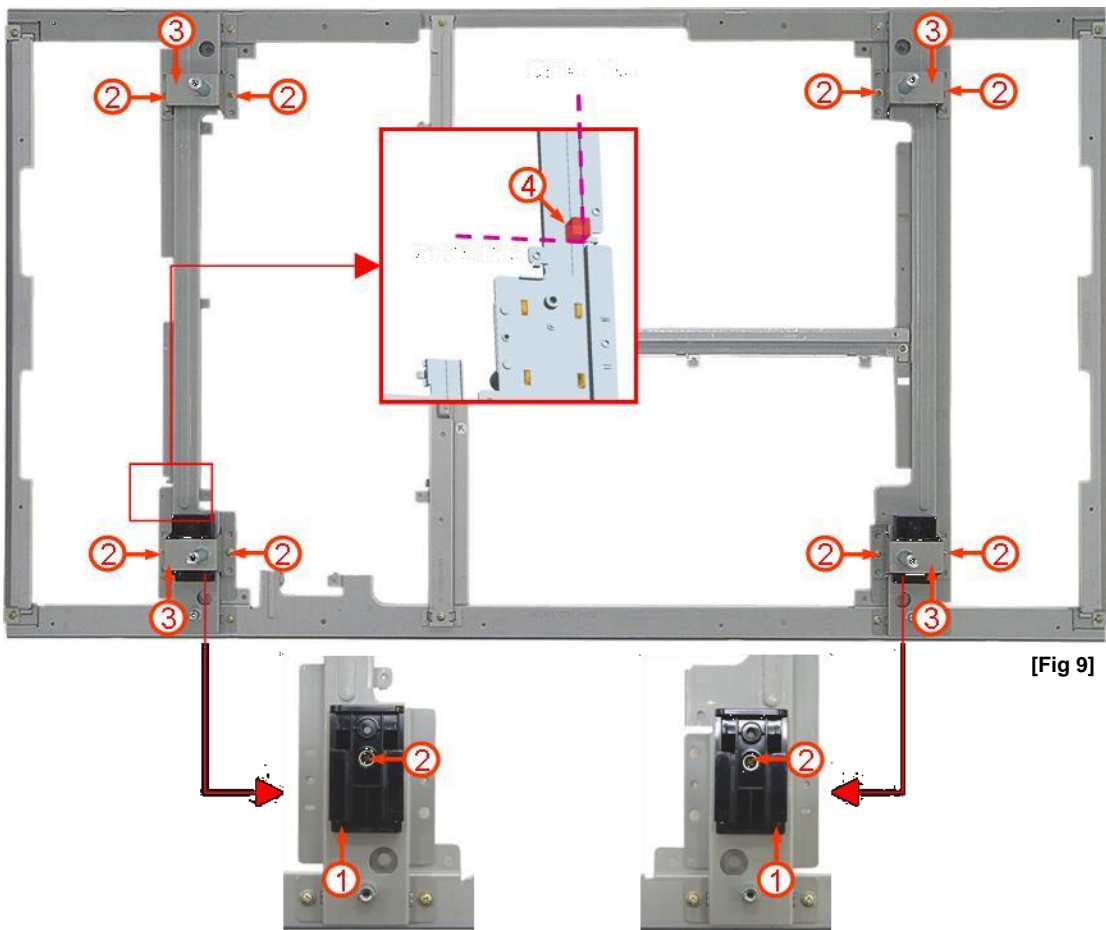
[Fig 6]

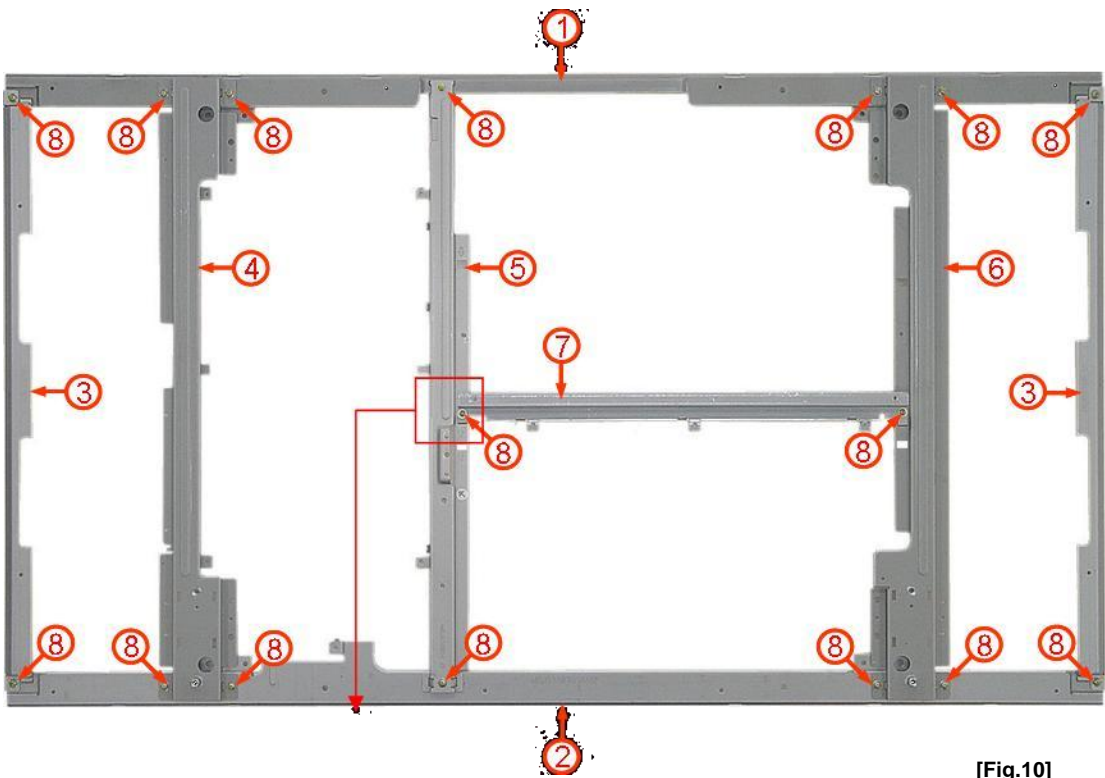


[Fig 7]

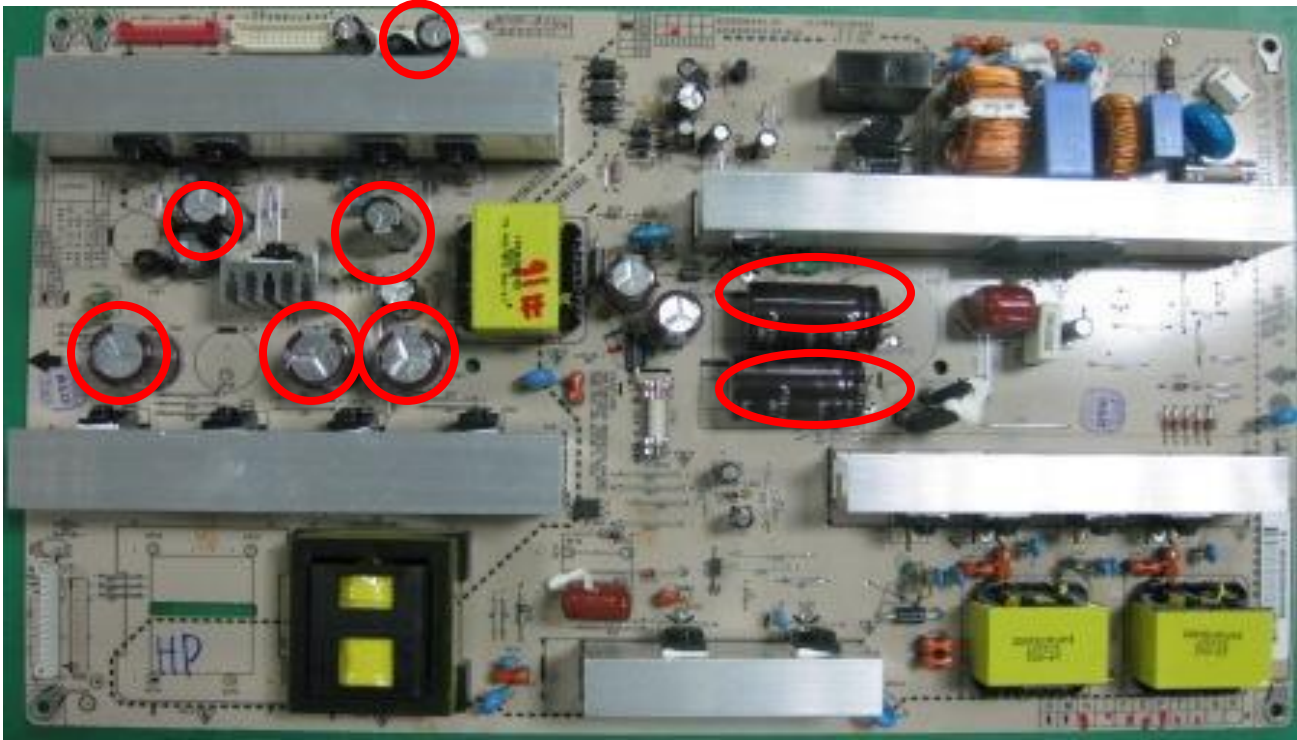


[Fig 8]





[Fig.10]



Designation	Main BD	Inverter BD	Power BD	TCON BD
Capacitors	39ea	4 ea	18ea	0ea
Electrolytic Capacitors (larger than 2.5cm)	0 ea	0ea	8 ea	0ea



<Main PCB>



<inverter Left PCB>



<inverter Right PCB>



< T-con PCB>



<Docking PCB>



<IR PCB>



< Key PCB>

